SEMICONDUCTOR DEVICE AND PACKAGING METHOD THEREOF

ABSTRACT OF THE DISCLOSURE

A semiconductor chip semiconductor device of the present invention is capable of obtaining a high-quality bare chip (HQC) easily and can retain quality without being affected by the surrounding environment. Electrodes (4) formed on the surface of a first resin sealed package (11) for sealing a semiconductor chip are connected to the electrodes of the semiconductor chip and each electrode (4) comprises a mounting area (101) to be connected to an object to be mounted and a testing area (102) for connecting testing equipment.

Fig. 5

This Sheet Has Been Replaced

